

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 1.00 mm (.039") Board to Board Connectors of System CB22	SPEC.NO.: SPCB053B
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA 364	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components , LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CB22***H100**

CB22*S100**

CB22*M100**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C. BOARD

0.8 mm (.031") ~ 1.6 mm (.063")



REVIEWED : Eisley APPROVED : Eisley VERIFIED : Sun .



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7. ELECTRICAL PERFORMANCE:

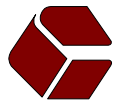
	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		2A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 500 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Single contact insertion force	Measure force to insertion using 0.30 mm square pin at speed 25± 3 mm per minute	250 gram Max Per Contact.
8.2	Single contact withdrawal force	Measure force to withdrawal using 0.30 mm square pin at speed 25± 3 mm per minute	25 gram Min Per Contact.
8.3	Durability	Connector shall be subjected to 250 cycles of insertion and withdrawal	Appearance: No damage

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Soldering time: 3 ± 0.5 sec Soldering pot: 240 ± 5 °C	Minimum: 95% of immersed area
9.2	Resistance to soldering heat	Lead-Free Wave Flow Process (For CB22***H100) Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5 °C Lead-Free IR Reflow Process: (CB22***S100/ CB22***M100) Soldering time: 7 ± 3 sec Soldering pot: 255 ± 5 °C	No damage



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	ITEM	TEST CONDITION	REQUIREMENT
9.3	Cold Resistance	-40 °C ± 3 °C, 96 hours	Appearance: No damage Contact resistance: Δ20 mΩ change
9.4	Heat Resistance	105 °C ± 3 °C, 96 hours	Appearance: No damage Contact resistance: Δ20 mΩ change
9.5	Temperature Cycling	5 cycles (1) -40 °C , 30 min. (2)Room temp. 10-15 min. (3) 105 °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Δ20 mΩ change
9.6	Salt Spray	Temperature: 35± 2 °C Solution: 5± 1% Spray time: 6± 1 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Δ20 mΩ max .

10. OPERATING TEMPERATURE : -40 °C to + 105 °C